

IN THE CLAIMS

Please amend the claims as follows:

Claims 15-28 (Cancelled).

Claim 29 (Currently Amended): A method for soldering an electronic part or printed board which comprises forming a coating film of ~~the composition as defined in Claim 15 a~~ composition on a part or the whole surface of an electronic part or a printed board, then treating the surface having the coating film thus formed, with a flux for soldering, and then carrying out soldering; wherein the composition comprises a polymer (A) containing polymer units (a¹) and polymer units (b¹), and an aqueous medium (B); wherein the polymer units (a¹) are derived from an unsaturated ester containing a polyfluoroalkyl group, or polymer units derived from an unsaturated ester containing a polyfluoroalkyl group having an etheric oxygen atom inserted in the carbon-carbon bond; and polymer units (b¹) derived from a compound containing a silicon atom and an unsaturated group.

Claim 30 (Currently Amended): A method for soldering an electronic part or printed board as claimed in claim 29; ~~which comprises forming a coating film of the composition as defined in Claim 23 on a part or the whole surface of an electronic part or a printed board, then treating the surface having the coating film thus formed, with a flux for soldering, and then carrying out soldering~~ wherein polymer (A) of the composition further comprises polymer units (c¹) other than the polymer units (a¹) and the polymer units (b¹); wherein the polymer units (c¹) are derived from a monomer containing a polymerizable unsaturated group, no R^f group, and no silicon atom.

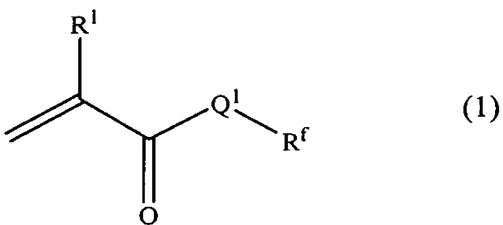
Claim 31 (Previously Presented): A soldered electronic part or printed board, obtained by the method as defined in Claim 29.

Claim 32 (Previously Presented): A soldered electronic part or printed board, obtained by the method as defined in Claim 30.

Claim 33 (Previously Presented): An electric appliance employing the electronic part or printed board as defined in Claim 31.

Claim 34 (Previously Presented): An electric appliance employing the electronic part or printed board as defined in Claim 32.

Claim 35 (New): A method for soldering an electronic part or printed board as claimed in claim 29, wherein the polymer units (a^1) of the composition are derived from a compound represented by the following formula (1):



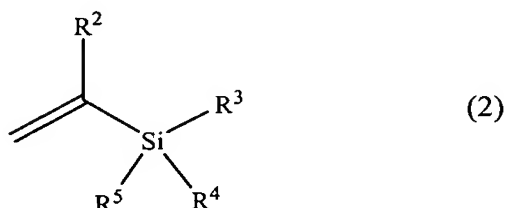
provided that in the formula (1), Q¹, R¹ and R^f have the following meanings:

Q¹ is a single bond or a bivalent connecting group,

R¹ is a hydrogen atom or a methyl group, and

R^f is a polyfluoroalkyl group, or a polyfluoroalkyl group having an etheric oxygen atom inserted in the carbon-carbon bond.

Claim 36 (New): A method for soldering an electronic part or printed board as claimed in claim 29, wherein the polymer unit (b^1) of the composition is a polymer unit of the compound having the following formula (2):

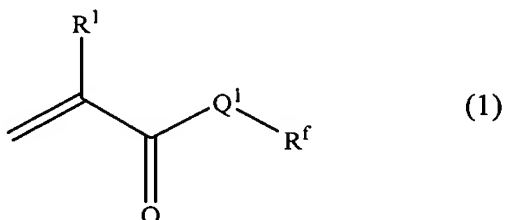


provided that in the formula (2), R², R³, R⁴ and R⁵ have the following meanings:

R² is a hydrogen atom or a methyl group and

R³, R⁴ and R⁵ are independent from one another, an alkyl group having a carbon number of from 1 to 5, or an alkoxy group having a carbon number of from 1 to 5.

Claim 37 (New): A method for soldering an electronic part or printed board as claimed in claim 29, wherein the polymer units (a^1) are derived from a compound represented by the following formula (1):



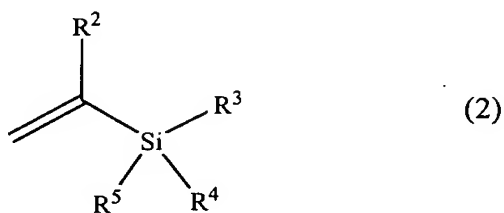
provided that in the formula (1), Q¹, R¹ and R^f have the following meanings:

Q¹ is a single bond or a bivalent connecting group,

R¹ is a hydrogen atom or a methyl group, and

R^f is a polyfluoroalkyl group, or a polyfluoroalkyl group having an etheric oxygen atom inserted in the carbon-carbon bond, and wherein

the polymer units (b^1) are derived from a compound having the following formula (2):



provided that in the formula (2), R², R³, R⁴ and R⁵ have the following meanings:

R² is a hydrogen atom or a methyl group and

R³, R⁴ and R⁵ are independent from one another, an alkyl group having a carbon number of from 1 to 5, or an alkoxy group having a carbon number of from 1 to 5.

Claim 38 (New): A method for soldering an electronic part or printed board as claimed in claim 29, wherein the polymer (A) further comprises a fluorine type surfactant (C).

Claim 39 (New): A method for soldering an electronic part or printed board as claimed in claim 29, wherein the softening point of the polymer (A) is at least 40°C and less than 150°C.

Claim 40 (New): A method for soldering an electronic part or printed board as claimed in claim 29, wherein the aqueous medium (B) contains a water-soluble organic solvent, and the boiling point of the water-soluble organic solvent is from 40 to 200°C.

Claim 41 (New): A method for soldering an electronic part or printed board as claimed in claim 29, wherein the surface tension of the composition is from 10 to 25 mN/m.

Claim 42 (New): A method for soldering an electronic part or printed board as claimed in claim 35, wherein the polymer (A) of the composition further comprises polymer units (c^1) other than the polymer units (a^1) and the polymer units (b^1); wherein the polymer units (c^1) are derived from a monomer containing a polymerizable unsaturated group, with no R^f group and no silicon atom.

Claim 43 (New): A method for soldering an electronic part or printed board as claimed in claim 36, wherein the polymer (A) further comprises polymer units (c^1) other than the polymer units (a^1) and the polymer units (b^1); wherein the polymer units (c^1) are derived from a monomer containing a polymerizable unsaturated group, with no R^f group and no silicon atom.

Claim 44 (New): A method for soldering an electronic part or printed board as claimed in claim 37, wherein the polymer (A) further comprises polymer units (c^1) other than the polymer units (a^1) and the polymer units (b^1); wherein the polymer units (c^1) are derived from a monomer containing a polymerizable unsaturated group, with no R^f group and no silicon atom.

Claim 45 (New): A method for soldering an electronic part or printed board as claimed in claim 30, wherein the polymer units (c^1) are polymer units derived from at least one monomer selected from the group consisting of ethylene, vinyl chloride, styrene, (meth)acrylic acid, cyclohexyl (meth)acrylate, an alkyl (meth)acrylate, a mono(meth)acrylate of a polyoxyalkylene diol, and glycidyl (meth)acrylate.

Claim 46 (New): A method for soldering an electronic part or printed board as claimed in claim 42, wherein the polymer units (c^1) are polymer units derived from at least one monomer selected from the group consisting of ethylene, vinyl chloride, styrene, (meth)acrylic acid, cyclohexyl (meth)acrylate, an alkyl (meth)acrylate, a mono(meth)acrylate of a polyoxyalkylene diol, and glycidyl (meth)acrylate.

Claim 47 (New): A method for soldering an electronic part or printed board as claimed in claim 43, wherein the polymer units (c^1) are polymer units derived from at least one monomer selected from the group consisting of ethylene, vinyl chloride, styrene, (meth)acrylic acid, cyclohexyl (meth)acrylate, an alkyl (meth)acrylate, a mono(meth)acrylate of a polyoxyalkylene diol, and glycidyl (meth)acrylate.

Claim 48 (New): A method for soldering an electronic part or printed board as claimed in claim 44, wherein the polymer units (c^1) are polymer units derived from at least one monomer selected from the group consisting of ethylene, vinyl chloride, styrene, (meth)acrylic acid, cyclohexyl (meth)acrylate, an alkyl (meth)acrylate, a mono(meth)acrylate of a polyoxyalkylene diol, and glycidyl (meth)acrylate.

Claim 49 (New): A method for soldering an electronic part or printed board as claimed in claim 30, wherein the polymer units (a^1) are polymer units derived from R^f -OCOCH=CH₂, the polymer units (b^1) are polymer units derived from CH₂=CHSi(OR⁶)₃, and the polymer units (c^1) are polymer units derived from cyclohexyl(meth)acrylate, wherein

R^f is a polyfluoroalkyl group, or a polyfluoroalkyl group having an etheric oxygen atom inserted in the carbon-carbon bond and

R^6 is an alkyl group having a carbon number of from 1 to 3.

DISCUSSION OF THE AMENDMENT

Claims 15-28 are cancelled without prejudice.

Claims 29 and 30 are amended to include the limitations of composition claims 15 and 23, respectively; wherein claims 15 and 23 were presented to the Office in the Preliminary Amendment filed on March 4, 2002.

Claims 31-34 were previously presented in said Preliminary Amendment.

Claims 35-49 are added.

Support for the amendment to the claims is found in the original claims as outlined in the following table:

New Claim	is dependent on claim	and has support in claim.
35	29	16
36	29	17
37	29	18
38	29	19
39	29	20
40	29	21
41	29	22
42	35	24
43	36	25
44	37	26
45	30	27
46	42	27
47	43	27
48	44	27
49	30	28

No new matter will be added upon entry of the amendment.

Upon entry of the amendment, claims 29-49 will be active.